**PATENT** S/N 09/483,881

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Kie Y. Ahn et al.

Examiner: Ha T. Nguyen

Serial No.:

09/483,881

Group Art Unit: 2812

Filed:

January 18, 2000

Docket: 303.672US1

Title:

SELECTIVE ELECTROLESS-PLATED COPPER METALLIZATION

# COMMUNICATION CONCERNING RELATED APPLICATION(S)

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Applicants would like to bring to the Examiner's attention the following related application(s) in the above-identified patent application:

Serial/Patent No. 10/929251	Filing Date August 30, 2004	Attorney Docket 303.672US2	Title SELECTIVE ELECTROLESS-PLATED COPPER METALLIZATION
10/931541	August 31, 2004	303.648US2	METHODS FOR MAKING INTEGRATED-CIRCUIT WIRING FROM COPPER, SILVER, GOLD, AND OTHER METALS

Respectfully submitted,

KIE Y. AHN ET AL.

By Applicants' Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

P.O. Box 2938

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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal 

Name

<u>S/N 09/483,881</u> <u>PATENT</u>

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#### SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

MS Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 et. seq., the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Supplemental Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Pursuant to 37 C.F.R. §1.97(c)(2), please charge Deposit Account No. 19-0743 in the amount of \$180.00 as set forth in 37 C.F.R. §1.17(p).

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The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

KIE Y. AHN ET AL.

By their Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A. P.O. Box 2938 Minneapolis, MN 55402

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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: MS Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this **ZZ** day of December, 2004.

Name

PTO/SB/08A(10-01)
Approved for use through 10/31/2002. OMB 051-0031
US Patent & Trademark Office U.S. DEPARTMENT OF COMMERCE.
Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid OMB control number. Substitute for form 1449A/PTO Complete if Known INFORMATION DISCLOSURE **Application Number** 09/483,881 STATEMENT BY APPLICANT January 18, 2000 **Filing Date** (Use as many sheets as necessary) Ahn, Kie **First Named Inventor Group Art Unit** 2812 Nguyen, Ha **Examiner Name** Attorney Docket No: 303.672US1

US PATENT DOCUMENTS						
Examiner Initial *			Name of Patentee or Applicant of cited Document	Filing Date If Appropriate		
	US- 2004/0206308 A1	10/21/2004	Ahn, K. Y., et al.	05/07/2004		
	US-6,103,320	08/15/2000	Matsumoto, S., et al.	06/09/1998		

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